

L Number	Hits	Search Text	DB	Time stamp
1	252915	((dambar tiebar (dam tie) adj32 bar) leadframe lead (lead adj frame) terminal) with (hollow indent indentions indenting grooves depression slope concave valley half etched etching hole ditch furrow channel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/08 14:45
2	2181677	semiconductor chip die ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/08 14:46
3	32265	((dambar tiebar (dam tie) adj32 bar) leadframe lead (lead adj frame) terminal) with (hollow indent indentions indenting grooves depression slope concave valley half etched etching hole ditch furrow channel)) same (semiconductor chip die ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/08 14:48
4	10545	((((dambar tiebar (dam tie) adj32 bar) leadframe lead (lead adj frame) terminal) with (hollow indent indentions indenting grooves depression slope concave valley half etched etching hole ditch furrow channel)) same (semiconductor chip die ic (integrated adj circuit))) and (wires wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/08 14:49
5	1124	(((((dambar tiebar (dam tie) adj32 bar) leadframe lead (lead adj frame) terminal) with (hollow indent indentions indenting grooves depression slope concave valley half etched etching hole ditch furrow channel)) same (semiconductor chip die ic (integrated adj circuit))) and (wires wire)) and (diepad paddle (die adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/08 14:50